Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently amended) A surface-mountable leadframe-based housing for ~~a surface-mountable~~ an electronic component, with a leadframe having a front side and a back side and comprising at least two electrical connector strips, and an injection-molded or transfer-molded housing base body made from an electrically insulating injection compound and comprising a front portion disposed at the front side of said leadframe and a back wall disposed at the back side of said leadframe, wherein said leadframe comprises at least one injection aperture through which said housing base body is injected onto said leadframe from a back side of said leadframe, and wherein the back wall of the housing base body includes a first recess that extends from said injection aperture.

2. (Previously Presented) The housing as described in claim 1, wherein said injection aperture is disposed in one of said electrical connector strips.

3. (Previously Presented) The housing as described in claim 1, wherein said back wall has a thickness of less than 0.3 mm and more than 0 mm.

4. (Currently amended) The housing as described in claim 1 for a radiation-emitting and/or radiation-detecting component, wherein said housing base body comprises in said front portion a second recess for receiving a radiation-emitting and/or radiation-detecting chip, said injection aperture being disposed in the region of a wall of said front portion delimiting said second recess.

5. (Currently amended) The housing as described in claim 4, wherein said second recess is formed as a reflector.

6. (Previously Presented) A leadframe ribbon comprising at least one housing as described in claim 1.

7. (Previously Presented) An electronic component having a housing as described in claim 1, which comprises at least one chip.

8. (Previously Presented) The electronic component as described in claim 7, wherein said at least one chip is a radiation-emitting and/or radiation-detecting chip.

9. (Previously Presented) The electronic component as described in claim 7, wherein said chip is disposed on one of the two connector strips and is electrically connected to the second connector strip by means of an electrical connecting line.

10. (Previously Presented) The electronic component as described in claim 7, wherein said chip is disposed on a mounting area of said housing base body and is electrically connected to each of said electrical connector strips by means of in each case one electrical connecting line.

11. (Previously Presented) The electronic component as described in claim 7, wherein said chip is disposed on a thermally well-conducting chip carrier leading through said housing base body to the back side and is electrically connected to each of said electrical connector strips by means of in each case one electrical connecting line.

12. (Currently amended) The ~~electronic component~~ housing as described in claim [[1]] 4, wherein said second recess is filled with an injection compound that is transparent to radiation emitted by and/or to be detected by said chip.

13. (Currently amended) A method for producing a leadframe-based housing ~~as described in claim 1,~~ comprising ~~the following method steps~~:

a) ~~preparing said~~ providing a leadframe comprising ~~said~~ two connector strips, at least one of the connector strips having ~~and said~~ an injection aperture,

b) applying to said leadframe an injection mold that forms around said leadframe a cavity for creating ~~said~~ a housing base body and ~~inserting~~ placing an injection nozzle ~~into or placing it against~~ proximate to said injection aperture,

c) injecting ~~the~~ an injection compound into said cavity,

d) ~~at least partially solidifying~~ causing the injection compound to at least partially solidify, and

e) removing the injection nozzle, and opening the injection mold~~, including the removal of said injection nozzle~~.

14. (Original) The method as described in claim 13, wherein a thermoplastic material is used as the injection compound.

15. (Previously Presented) The electronic component comprising a housing with reference to claim 4, wherein said recess is filled with an injection compound that is transparent to radiation emitted by and/or to be detected by said chip.